



Material Content Data Sheet



Sales Product Name	TLE8104E			Issued	28. August 2013			
MA#	MA001046042							
Package	PG-DSO-20-71			Weight*	597.92 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.446	1.75	1.75	17471	17471
leadframe	inorganic material	phosphorus	7723-14-0	0.051	0.01		85	
	non noble metal	zinc	7440-66-6	0.203	0.03		339	
	non noble metal	iron	7439-89-6	4.058	0.68		6786	
wire	non noble metal	copper	7440-50-8	164.755	27.55	28.27	275547	282757
	non noble metal	copper	7440-50-8	1.343	0.22	0.22	2247	2247
	encapsulation	organic material	carbon black	1333-86-4	0.817	0.14		1367
encapsulation	plastics	epoxy resin	-	37.587	6.29		62863	
	inorganic material	silicondioxide	60676-86-0	370.153	61.90	68.33	619067	683297
leadfinish	non noble metal	tin	7440-31-5	4.487	0.75	0.75	7504	7504
plating	noble metal	silver	7440-22-4	0.767	0.13	0.13	1283	1283
glue	plastics	epoxy resin	-	0.813	0.14		1360	
	noble metal	silver	7440-22-4	2.440	0.41	0.55	4081	5441
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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